

Title (en)

ELECTROLESS PALLADIUM PLATING SOLUTION, AND ELECTROLESS PALLADIUM PLATED COATING

Title (de)

LÖSUNG ZUR STROMLOSEN ABSCHIEDUNG VON PALLADIUM UND BESCHICHTUNG MIT STROMLOSER PALLADIUMABSCHIEDUNG

Title (fr)

SOLUTION DE DÉPOSITION AUTOCATALYTIQUE DE PALLADIUM, ET FILM DE REVÊTEMENT DE DÉPOSITION AUTOCATALYTIQUE DE PALLADIUM

Publication

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Application

EP 18864662 A 20181003

Priority

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- JP 2018036970 W 20181003

Abstract (en)

An object of the present invention is to provide an electroless Pd plating solution which enables formation of a Pd plating film forming a plating film having excellent wire bondability even after a high-temperature thermal history. An electroless Pd plating solution of the present invention solved above problems, the solution includes a Palladium compound, at least one selected from a group consisting of a hypophosphorous acid compound and a phosphorous acid compound, at least one selected from the group consisting of an amine borane compound and a hydroboron compound, and a complexing agent.

IPC 8 full level

C23C 18/44 (2006.01)

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